

CHIP MANUFACTURING METHOD

ABSTRACT OF THE DICLOSURE

A chip manufacturing method for manufacturing a plurality of chips by dividing a wafer containing Si, the wafer having a front side on which a plurality of division lines are formed to define a plurality of separate regions where a plurality of devices are respectively formed, a metal layer containing Cu being formed on each division line ,the chip manufacturing method includes a laser processed groove forming step of applying a laser beam to the front side of the wafer along each division line thereby removing the metal layer and forming a laser processed groove on the front side of the wafer along each division line, an enlargement promoting step of promoting the enlargement of debris generated by the formation of the laser processed groove and adhering to the inside surface of the laser processed groove, and a dividing step of dividing the wafer along the laser processed groove.

FIGURE 6B